



Material Content Data Sheet



Sales Product Name		BGA 748L16 E6327		Issued		20. July 2018		
MA#		MA001129930						
Package		PG-TSLP-16-1		Weight*		7.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.268	3.67	3.67	36667	36667
leadframe	non noble metal	nickel	7440-02-0	2.483	33.98	33.98	339847	339847
wire	noble metal	gold	7440-57-5	0.099	1.36	1.36	13600	13600
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.002	0.03		273	
	organic material	carbon black	1333-86-4	0.040	0.55		5457	
	plastics	epoxy resin	-	0.538	7.37		73667	
encapsulation	inorganic material	silicondioxide	60676-86-0	3.407	46.62	54.57	466281	545678
	noble metal	gold	7440-57-5	0.131	1.79	1.79	17945	17945
plating	noble metal	silver	7440-22-4	0.214	2.93	2.93	29304	29304
glue	plastics	epoxy resin	-	0.025	0.34		3392	
	noble metal	silver	7440-22-4	0.099	1.36	1.70	13567	16959
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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